IN THE CLAIMS:

1. (currently amended) A transport and storage carrier for semiconductor members including wafers which is characterized in that the carrier is molded from a resin composition comprising a synthetic resin having a melting temperature of at least 300°C and a carbon fibril admixed with the resin, the ~~molded~~ carrier ~~being 1 to 5 seconds in~~ having an average charge decay time of 1 to 5 seconds for a charge decay of 1,000 V to 5 V, and wherein said carbon fibril is 3.5 to 75 nm in average diameter and ~~5 to 1000~~ 5 to 1333 in aspect ratio, and further wherein said synthetic resin is a polyetheretherketone or a polyetherimide.

2 - 3. (canceled)

4. (original) A carrier according to claim 1 wherein 1 to 10 parts by weight of the carbon fibril is used per 100 parts by weight of the synthetic resin.

5. (currently amended) A transport and storage carrier for semiconductor members including wafers which is characterized in that the carrier is molded from a resin composition consisting essentially of a synthetic resin having a melting temperature of at

least 300°C and carbon fibril having an average diameter of 3.5 to 75 nm and an aspect ratio of ~~5 to 1000~~ 5 to 1333 admixed with the resin, the ~~molded~~ carrier ~~being 1 to 5 seconds in~~ having an average charge decay time of 1 to 5 seconds for a charge decay of 1,000 V to 5 V, and wherein said synthetic resin is polyetheretherketone or polyetherimide.

6. (canceled).

7. (previously presented) A carrier according to claim 5, wherein 1 to 10 parts by weight of the carbon fibril is used per 100 parts by weight of the synthetic resin.